



TECHNICAL DATA SHEET

CATEGORY: **NO-CLEAN SOLDER PASTE**
 NAME: **NR-116+**
 ALLOY: SAC (Tin-Silver-Copper)

FEATURES

- NO VISIBLE RESIDUE
- DESIGNED FOR NITROGEN REFLOW
- RESIN/ROSIN-FREE
- GOOD WETTING CHARACTERISTICS

* Passes BELLCORE and IPC, product testing results available upon request

DESCRIPTION

NR-116+ offers improved slump resistance and tack force. NR-116+ is a no-visible-residue solder paste developed for use in nitrogen reflow applications. As a resin-free / rosin-free no-clean product, any remaining post-process residues may be left on the PCB without degradation. This material has been utilized on various assemblies with RF designs without cleaning; however, the compatibility of flux residues on RF assemblies is strongly dependent upon circuitry design.

STANDARD PASTE COMPOSITION

| Application Method | IPC Powder Type | Metal Load |
|-----------------------------------|-----------------|------------|
| Standard Stencil Printing | 3 | 88.5% |
| Fine Pitch Stencil Printing | 5 | 88% |
| Ultra-Fine Pitch Stencil Printing | 5 | 87.5% |
| Dispensing syringes | 3 | 84% |

Note: These are typical starting guidelines. To achieve optimal performance, actual metal load and particle size may vary per process, application, and environment.

HANDLING

- NR-116+ has a refrigerated shelf life of 3 months.
Do not freeze this product.
- Allow the solder paste to warm completely and naturally to ambient temperature (8 hours is recommended) prior to breaking the seal for use.
- Mix the product lightly and thoroughly for 1 to 2 minutes to ensure an even distribution of any separated material resulting from storage.
- Do not store new and used paste in the same container. Re-seal any opened containers while not in use.

PRINTER SETUP

Following are the suggested starting parameters for your screen printer. Some assumptions were made as to the printer types used in today's applications. Adjustments will vary between equipment, application and facility environment.

| | | | |
|-------------------------|---------------------------|---|-------------------------------|
| SNAP-OFF DISTANCE | ON CONTACT (0.00") | SQUEEGEE PRESSURE | 1-1.5 LBS/IN. OF BLADE |
| PCB SEPARATION DISTANCE | .030-.050" | SQUEEGEE STROKE SPEED | .5 - 6 IN/SEC * |
| PCB SEPARATION SPEED | MEDIUM | * DEPENDENT ON PCB AND PAD DESIGNS | |

